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Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

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- *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*

(54) **Title:** COMPOSITE AND MULTILAYERED SILVER FILMS FOR JOINING ELECTRICAL AND MECHANICAL COMPONENTS

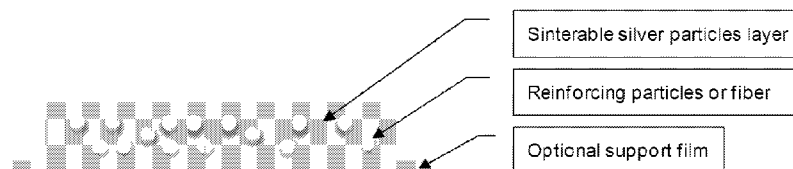


FIG. 2

(57) **Abstract:** Materials for die attachment such as silver sintering films may include reinforcing, modifying particles for enhanced performance. Methods for die attachment may involve the use of such materials.

